

## Specification of SMD Digital Microphone (RoHS Compliance & Halogen Free)

Customer Name :  
Customer Model :  
Goermicro Model : SD18OB371-077

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## 1 Introduction

MEMS MIC which is able to endure reflow temperature up to 260°C for 50 seconds can be used in SMT process. It is widely used in telecommunication and electronics device such as mobile phone, laptop computers, and other portable electronic devices etc.

## 2 Test Condition ( $V_{DD}=1.8V$ , $f_{CLK}=2.4MHz/768kHz/1.024MHz$ , $L=50\text{ cm}$ )

StandardConditions (As IEC 60268-4)	Temperature	Humidity	Air pressure
Environment Conditions	+15°C~+35°C	25%RH~75%RH	86kPa~106kPa
Basic Test Conditions	+20°C±2°C	60%RH~70%RH	86kPa~106kPa

## 3 Acoustic and Electrical Characteristics

### 3.1 Standard Mode

(Test Condition:  $V_{DD}=1.8V$ ,  $f_{CLK}=2.4MHz$ , Decimation=64X)

Item	Symbol	Test Conditions	Min	Typ	Max	Unit
Sensitivity	S	94dBSPL@1kHz	-38	-37	-36	dBFS (Note 1)
Current Consumption (Note 2)	I	$f_{CLK}=2.4MHz$	-	800	1000	μA
S/N Ratio	SNR	94dBSPL@1kHz A-Weighting	-	66	-	dB
Distortion	THD	1%THD@1kHz	-	127	-	dB SPL
Acoustic Overload Point	AOP	10% THD@1kHz, S=Typ	-	132	-	dB SPL
Power Supply Rejection	PSR	100mVpp Squarewave @217Hz A-weighting	-	-101	-	dBFS
Low Frequency Roll-off	LFRO	-3dB corner refrence to 1kHz sensitivity	25	35	45	Hz

### 3.2 Low Power Mode

(Test Condition:  $V_{DD}=1.8V$ ,  $f_{CLK}=768kHz$ , Decimation=64X)

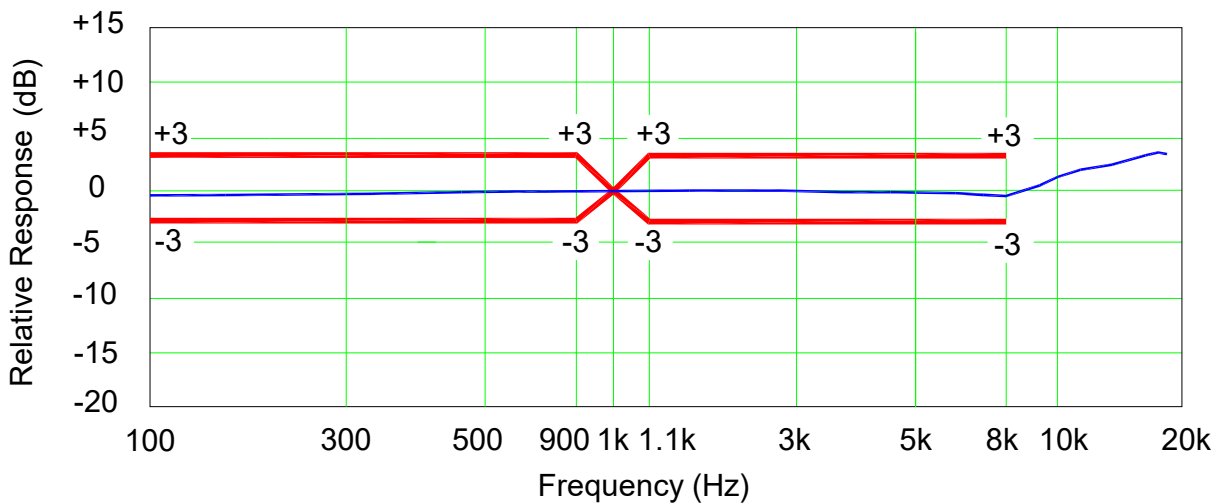
Item	Symbol	Test Conditions	Min	Typ	Max	Unit
Sensitivity	S	94dBSPL@1kHz	-22	-21	-20	dBFS (Note 1)
Current Consumption (Note 2)	I	$f_{CLK}=768kHz$	-	-	300	μA
S/N Ratio	SNR	94dBSPL@1kHz A-Weighting	-	66	-	dB
Distortion	THD	1%THD@1kHz	-	112	-	dB SPL
Acoustic Overload Point	AOP	10% THD@1kHz, S=Typ	-	117	-	dB SPL
Power Supply Rejection	PSR	100mVpp Squarewave @217Hz A-weighting	-	-83	-	dBFS

(Test Condition:  $V_{DD}=1.8V$ ,  $f_{CLK}=1.024MHz$ , Decimation=64X)

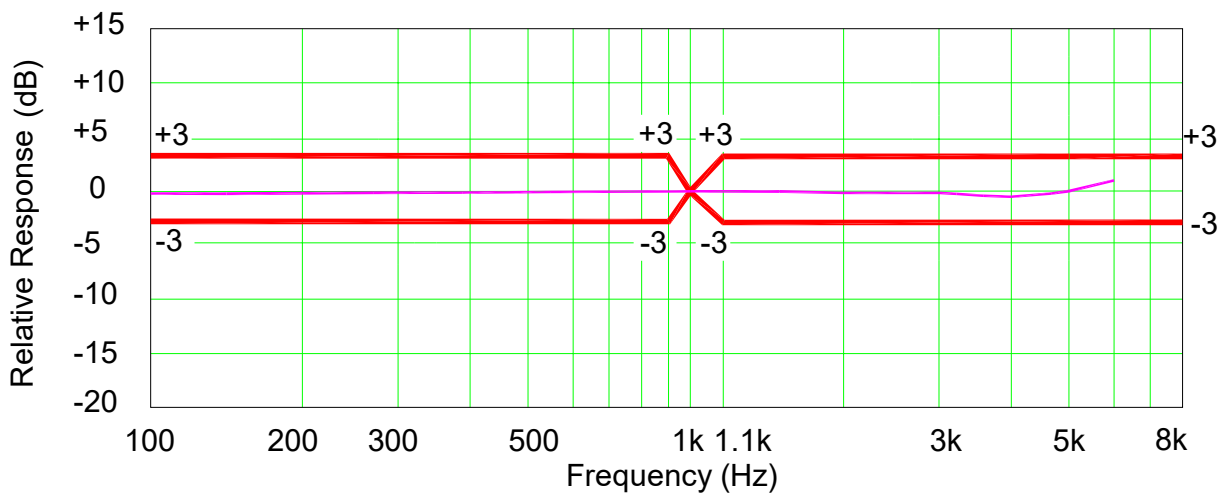
Item	Symbol	Test Conditions	Min	Typ	Max	Unit
Sensitivity	S	94dB SPL@1kHz	-22	-21	-20	dBFS (Note 1)
Current Consumption (Note 2)	I	$f_{CLK}=1.024MHz$	-	-	350	$\mu A$
S/N Ratio	SNR	94dB SPL@1kHz A-Weighting	-	66	-	dB
Distortion	THD	1% THD@1kHz	-	112	-	dB SPL
Acoustic Overload Point	AOP	10% THD@1kHz, S=Typ	-	117	-	dB SPL
Power Supply Rejection	PSR	100mVpp Squarewave @217Hz A-weighting	-	-83	-	dBFS

### 3.3 Frequency Response Curve and Limits

**Typical Free Field Response  
Normalized to 1kHz  
Standard Mode  $V_{DD}=1.8V$ ,  $f_{CLK}=2.4MHz$ , Decimation Rate=64x**



**Typical Free Field Response  
Normalized to 1kHz  
Low Power Mode  $V_{DD}=1.8V$ ,  $f_{CLK}=768kHz$ , Decimation Rate=64x**



### 3.4 Microphone Interface Specifications

Item	Symbol	Test Conditions	Min	Typ	Max	Unit
Input Logic High Level	$V_{IH}$		$0.65XV_{DD}$	-	$V_{DD}+0.3$	V
Input Logic Low Level	$V_{IL}$		-0.3	-	$0.3XV_{DD}$	V
Output Logic High Level	$V_{OH}$		$0.65XV_{DD}$	-	$V_{DD}+0.3$	V
Output Logic Low Level	$V_{OL}$		-0.3	-	$0.3XV_{DD}$	V
Clock Duty Cycle			40	-	60	%
Clock Rise/Fall Time	Low Power Mode	$t_{RF}$			250	nS
	Standard Mode				50	nS
Delay Time for Data Driven, VDD = 1.8V	$t_{DD}$	Delay time from CLOCK edge to DATA driven.	18	-	50	nS
Delay Time for Data High-Z, VDD = 1.8V	$t_{HZ}$	Delay time from CLOCK edge to DATA high impedance state.	5	-	16	nS
Delay Time for Data Valid	$t_{DV}$	Delay time from CLOCK edge to DATA valid (<0.30 x VDD or >0.70 x VDD)	-	-	100	nS

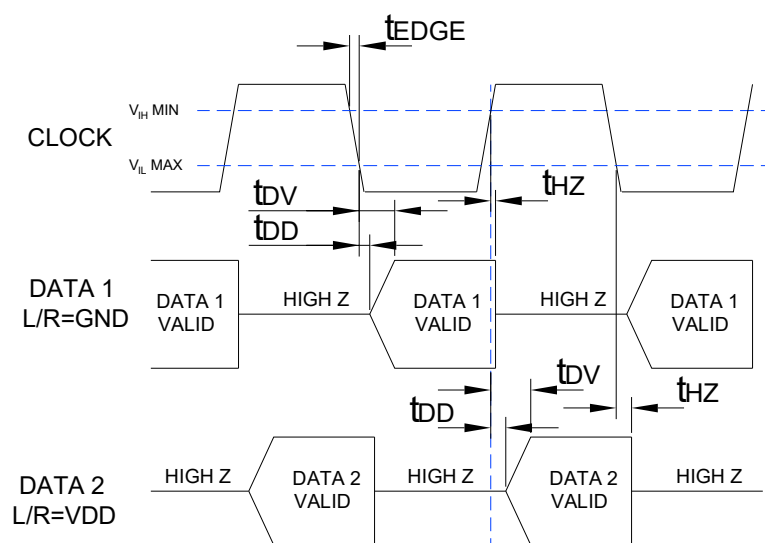
### 3.5 General Microphone Specifications

Item	Symbol	Test Conditions	Min	Typ	Max	Unit
Supply Voltage	$V_{DD}$		1.62	-	3.6	V
Clock Frequency Range	Standby Mode		0	-	150	kHz
	Low Power Mode		0.25	0.768	1.2	MHz
	Standard Mode		1.45	-	4.8	MHz
Directivity			Omni-directional			
Polarity		Increasing Sound	Increasing density of 1's			
Data Format			$\frac{1}{2}$ Cycle PDM 1bit			
Short Circuit Current		Grounded Data Pin	-	-	20	mA
Output Load Capacitance on DATA	$C_{load}$		-	-	140	pF
Start-up Time		Time to start up in either modes (Low Power- and Normal Mode) after VDD and CLOCK have been applied.	-	-	50	ms
Restart Time		Time to start up in either modes (Low Power- and Normal Mode) after VDD has been off for more than 10ms, while CLOCK remained on.	-	-	50	ms
Mode-Switch Time		Time to switch between modes (Clock off- Low Power-, and Normal Mode). VDD remains on during the mode switch.	-	-	50	ms

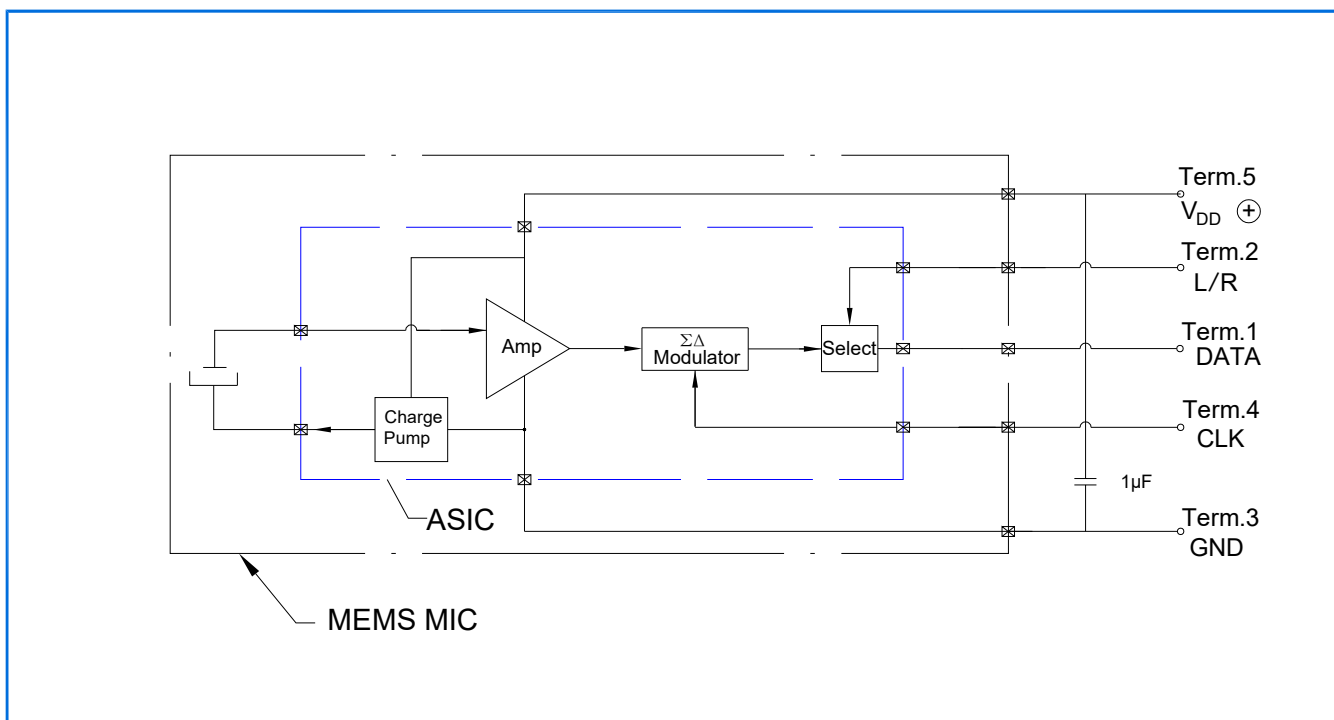
Note 1.  $dBFS = 20 \times \log(A/B)$  where A is the level of the signal, B is the level that corresponds to Full-scale level.

Note 2. The current consumption depends on the applied Clock Frequency and the load on the DATA output.

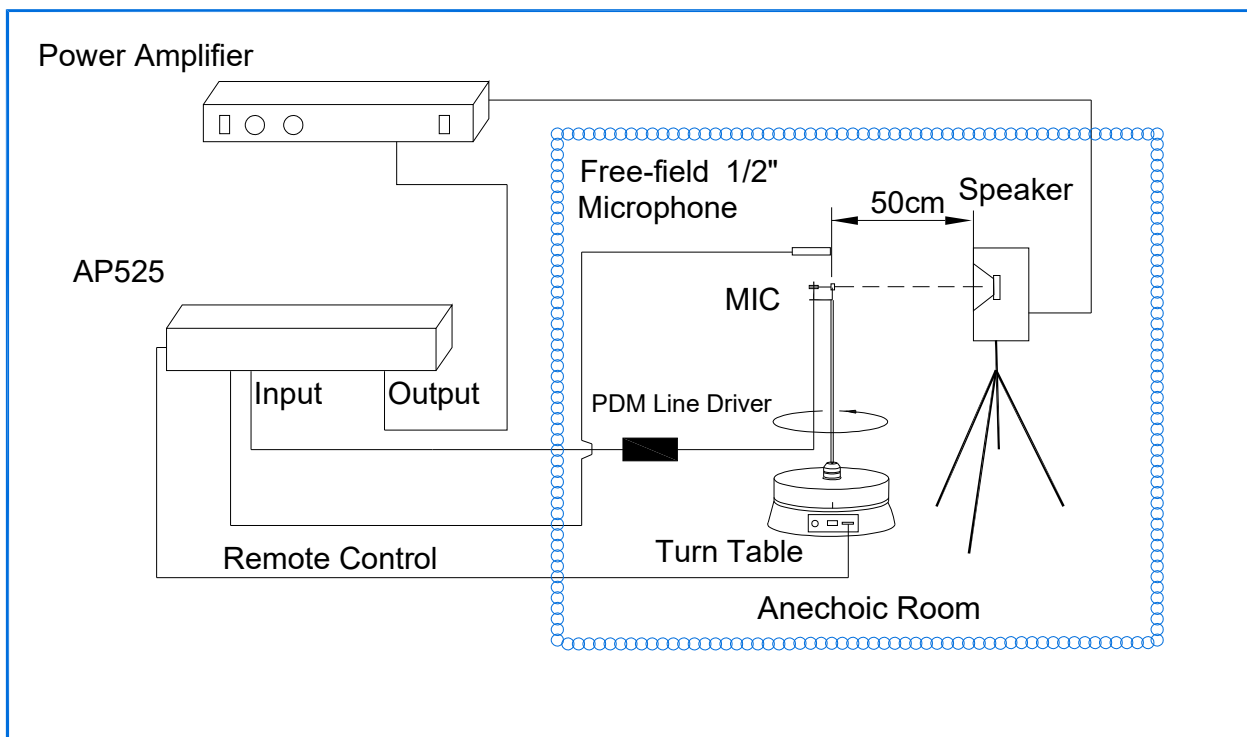
### Note 3. Timing



### 4 Measurement Circuit



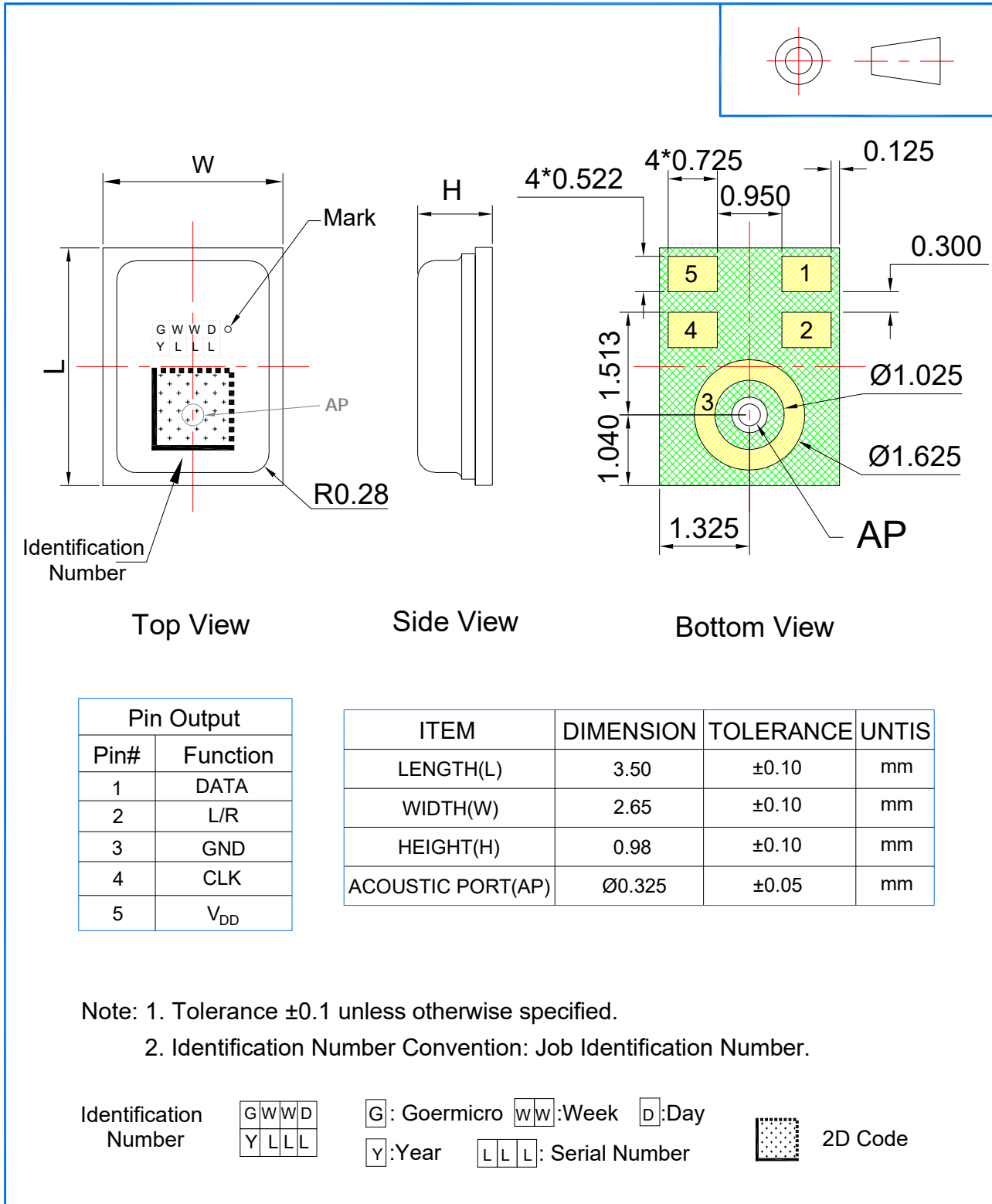
### 5 Test Setup Drawing





## 6 Mechanical Characteristics

### 6.1 Appearance Drawing (Unit: mm)



### 6.2 Weight

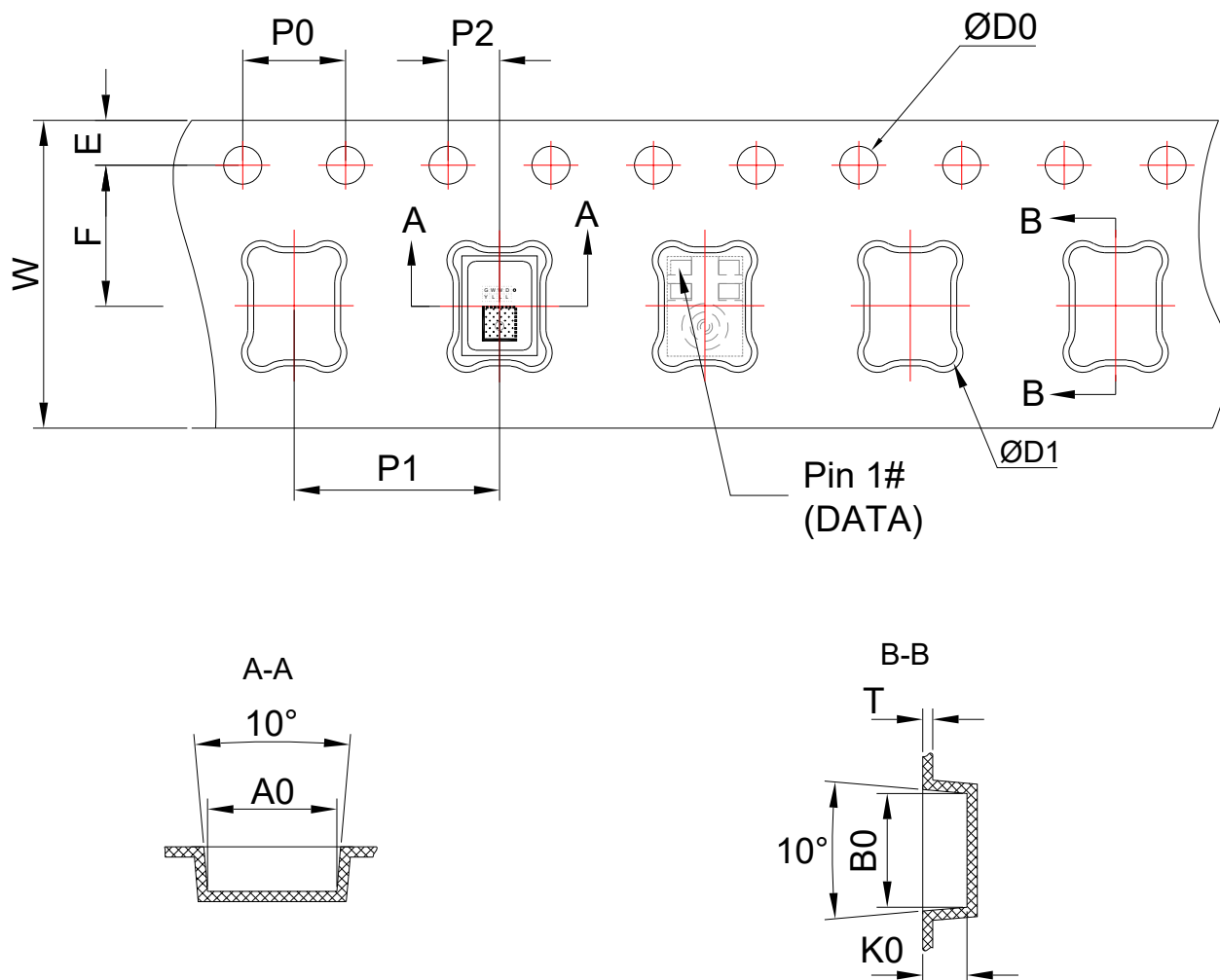
The weight of the MIC is Less than 0.05g.

## 7 Reliability Test

<p>7.1 Vibration Test</p>	<p>To be no interference in operation after vibrations, 4 cycles, from 20 to 2,000Hz in each direction(X,Y,Z), 48 minutes, using peak acceleration of 20g, sensitivity should vary within <math>\pm 3</math>dBFS from initial sensitivity. (The measurement to be done after 2 hours of condition at 15°C-35°C, R.H. 25%~75%)</p>
<p>7.2 Drop Test</p>	<p>To be no interference in operation after dropped to 1.0cm steel plate 12 times from 1.5 meter height in state of JIG,JIG weight of 100g, sensitivity should vary within <math>\pm 3</math>dBFS from initial sensitivity. (The measurement to be done after 2 hours of condition at 15°C-35°C, R.H. 25%~75%)</p>
<p>7.3 Temperature Test</p>	<p>a) After exposure at +125°C for 200 hours, sensitivity should vary within <math>\pm 3</math>dBFS from initial sensitivity. (The measurement to be done after 2 hours of condition at 15°C-35°C, R.H. 25%~75%)  b) After exposure at -40°C for 200 hours, sensitivity should vary within <math>\pm 3</math>dBFS from initial sensitivity. (The measurement to be done after 2 hours of condition at 15°C-35°C, R.H. 25%~75%)</p>
<p>7.4 Humidity Test</p>	<p>After exposure at +85°C and 85% relative humidity for 200 hours, sensitivity should vary within <math>\pm 3</math>dBFS from initial sensitivity. (The measurement to be done after 2 hours of condition at 15°C-35°C, R.H. 25%~75%)</p>
<p>7.5 Mechanical Shock Test</p>	<p>Then subject samples to three one-half sine shock pulses (3000 g for 0.3 milliseconds) in each direction (for six axes in total) along each of the three mutually perpendicular axes for a total of 18 shocks, sensitivity should vary within <math>\pm 3</math>dBFS from initial sensitivity. (The measurement to be done after 2 hours of condition at 15°C-35°C, R.H. 25%~75%)</p>
<p>7.6 Thermal Shock Test</p>	<p>After exposure at -40°C for 30 minutes, at +125°C for 30 minutes (change time 20 seconds) 32 cycles, sensitivity should vary within <math>\pm 3</math>dBFS from initial sensitivity. (The measurement to be done after 2 hours of condition at 15°C-35°C, R.H. 25%~75%)</p>
<p>7.7 Reflow Test</p>	<p>Adopt the reflow curve of item 12.3, after three reflows, sensitivity should vary within <math>\pm 2</math>dBFS from initial sensitivity. (The measurement to be done after 2 hours of condition at 15°C-35°C, R.H. 25%~75%)</p>
<p>7.8 Electrostatic Discharge Test</p>	<p>Under C=150pF, R=330ohm. Air discharge to case with <math>\pm 8</math>kV and contact discharge to I/O terminals with <math>\pm 2</math>kV, 10 times, Grounding. Sensitivity should vary within <math>\pm 3</math>dBFS from initial sensitivity.</p>

## 8 Package

### 8.1 Tape Specification



The Dimensions as Follows:

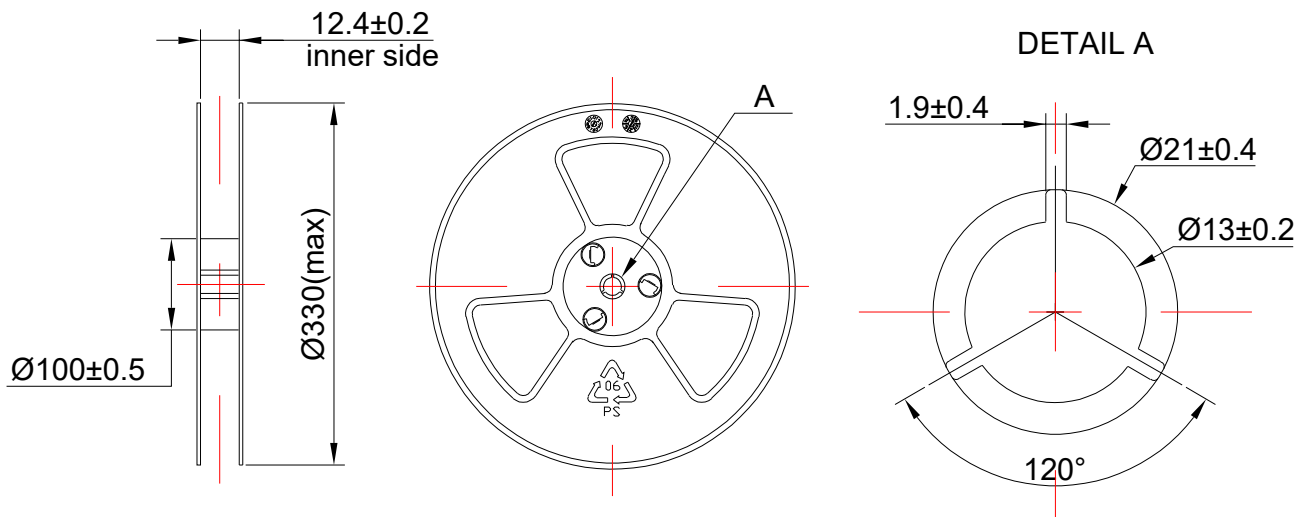
ITEM	W	E	F	ØD0	K0
DIM(mm)	12.0±0.30	1.75±0.10	5.5±0.05	1.50 <sup>+0.10</sup> <sub>0</sub>	1.30±0.10
ITEM	P0	10P0	P1	A0	B0
DIM(mm)	4.00±0.10	40.00±0.20	8.00±0.10	2.85±0.05	3.75±0.05
ITEM	P2	T			
DIM(mm)	2.00±0.05	0.30±0.05			

## 8.2 Reel Dimension

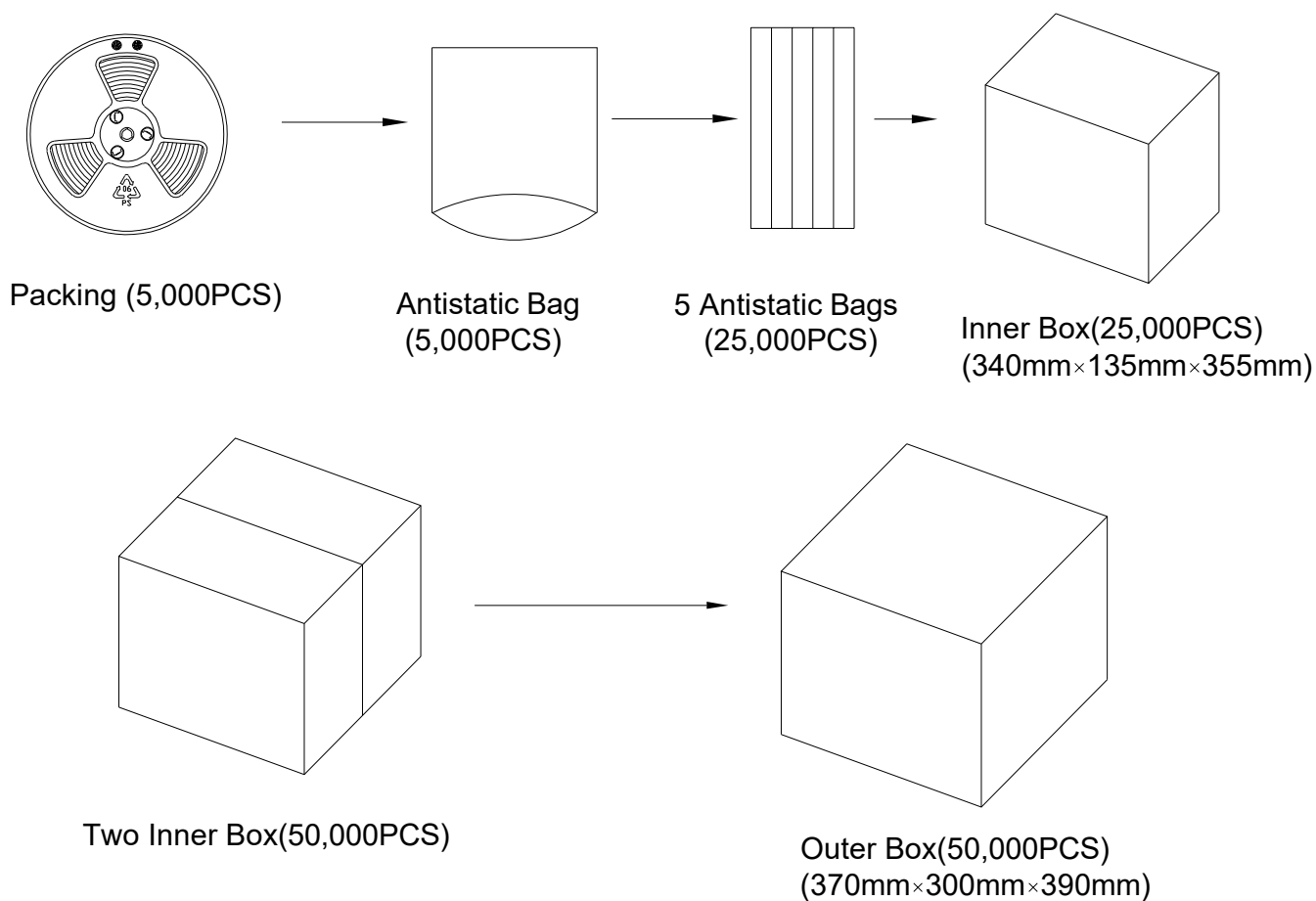
7" reel for sample stage

13" reel will be provided for the mass production stage

The following is 13" reel dimensions (unit:mm)

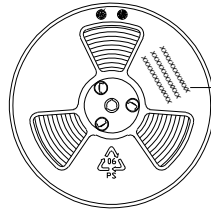


## 8.3 The Content of Box(13" reel)



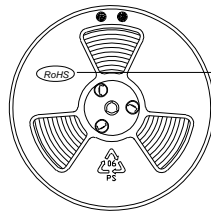
## 8.4 Packing Explain

### 8.4.1 The Label Content of the Reel



The Content Includes:  
Product type, Lot, Customer P/N;  
and other essential information such as  
Quantity, Date etc.

### 8.4.2 The RoHS Label



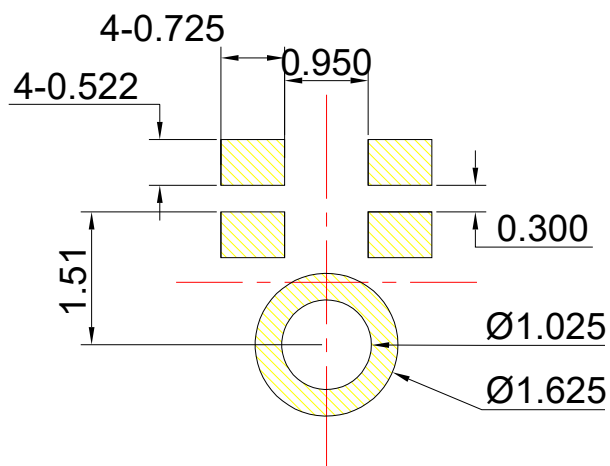
RoHS HF  
Compliance Mark

## 9 Storage and Transportation

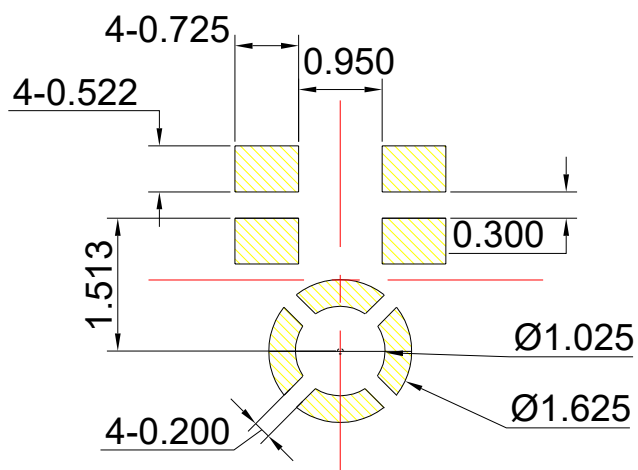
- 9.1 Keep MEMS MIC in warehouse with less than 75% humidity and without sudden temperature change, acid air, any other harmful air or strong magnetic field. Recommend storage period no more than 1 year and floor life(out of bag) at factory no more than 4 weeks.
- 9.2 The MEMS MIC with normal pack can be transported by ordinary conveyances. Please protect products against moist, shock, sunburn and pressure during transportation.
- 9.3 Storage Temperature Range:  $-40^{\circ}\text{C} \sim +70^{\circ}\text{C}$
- 9.4 Operating Temperature Range:  $-40^{\circ}\text{C} \sim +70^{\circ}\text{C}$

## 10 Land Pattern Recommendation

### 10.1 Recommended Land Pattern(Unit:mm)



### 10.2 Recommended Solder Stencil Pattern(Unit:mm)

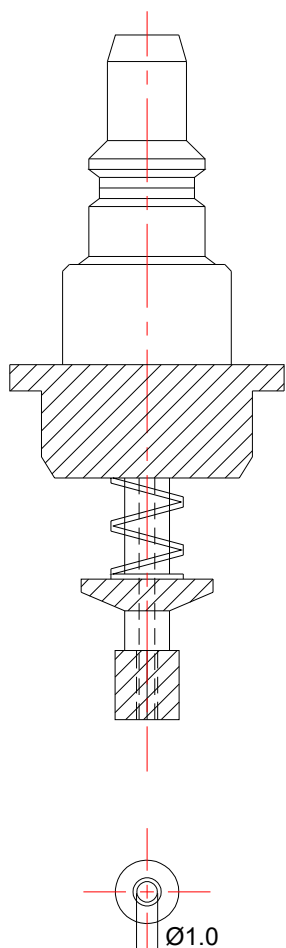


## 11 Soldering Recommendation

### 11.1 Soldering Machine Condition

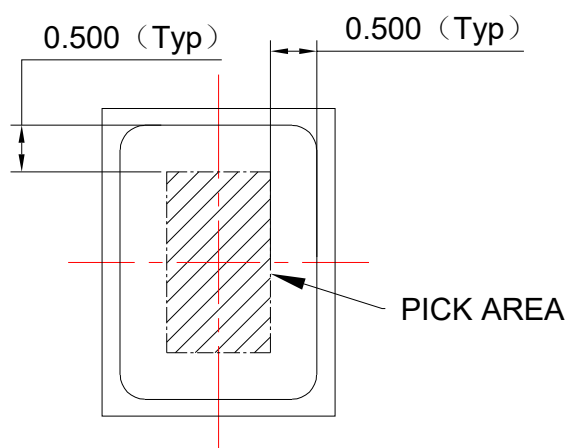
Temperature Control	8 zones
Heater Type	Hot Air
Solder Type	Lead-free

### 11.2 The Drawing and Dimension of Nozzle

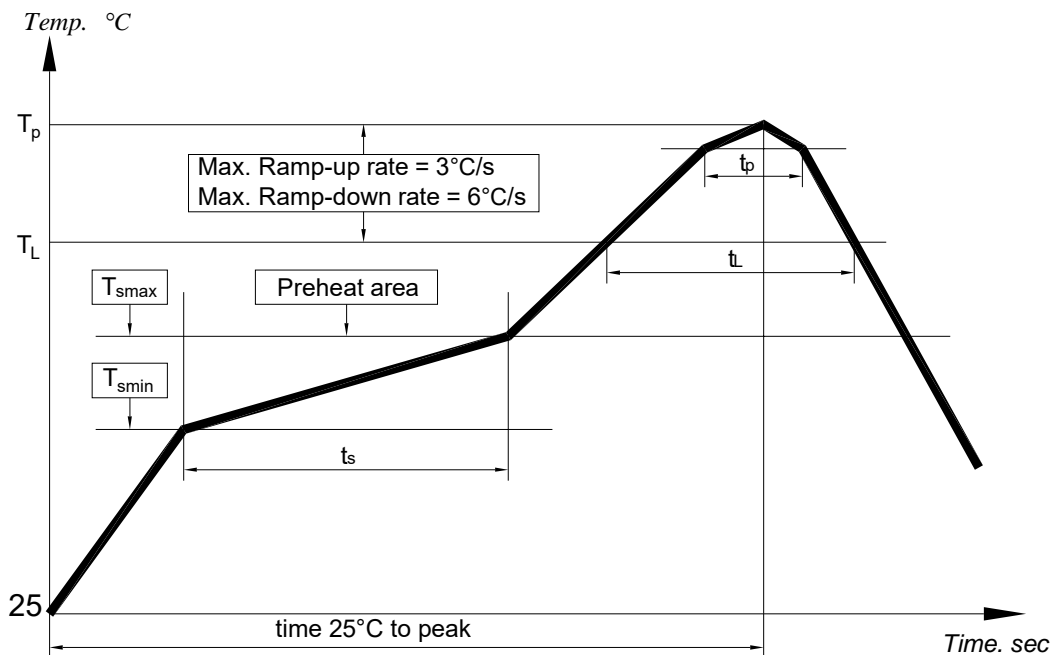


Inside Diameter:  $\varnothing 1.0\text{mm}$ ;  
 Acoustic Port:  $\varnothing 0.325\text{mm}$ ;  
 Vacuum Degree of Nozzle:  $-80\text{kPa} \sim -90\text{kPa}$ ;

Please don't vacuum over the acoustic port directly.  
 Please don't blow the acoustic port directly.



## 11.3 Reflow Profile



### Key Features of The Profile:

Average Ramp-up rate( $T_{smax}$ to $T_p$ )	3°C/s max.
Preheat : Temperature Min( $T_{smin}$ ) Temperature Max( $T_{smax}$ ) Time( $T_{smin}$ to $T_{smax}$ )( $t_s$ )	150°C 200°C 60~180s
Time maintained above : Temperature( $T_L$ ) Time( $t_L$ )	217°C 60~150s
Peak Temperature( $T_p$ )	260°C
Time within 5°C of actual Peak Temperature( $t_p$ ) :	30~40s
Ramp-down rate( $T_p$ to $T_{smax}$ )	6°C/s max
Time 25°C to Peak Temperature	8min max

When MEMS MIC is soldered on PCB, the reflow profile is set according to solder paste and the thickness of PCB etc.



## 12 Cautions

### 12.1 Board Wash Restrictions

It is very important not to wash this microphone, otherwise this could damage the microphone.

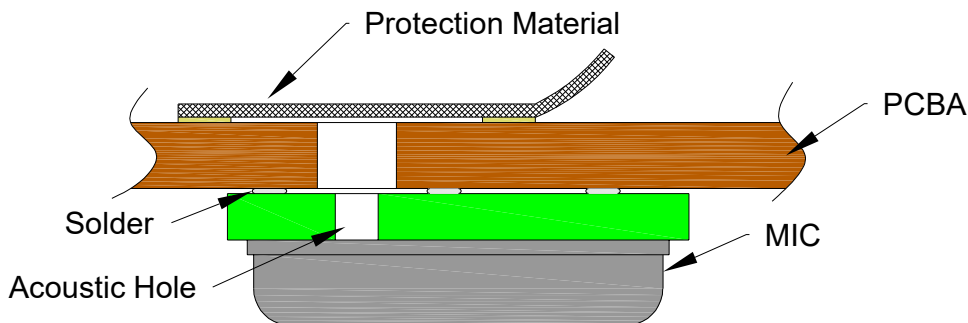
### 12.2 Ultrasonic Restrictions

It is very important not to use ultrasonic process. otherwise this could damage the microphone.

### 12.3 Acoustic Port Protection

It is very important not to operate vacuum and air blow into acoustic port(without any covering over acoustic port), otherwise this could damage the microphone. And it is necessary to be careful about foreign substances into acoustic port .Please add protection material (e.g. PET ) on the acoustic hole to protect it after SMT , refer to below pictures, take it away before test, then attach it again until the end of assembly.

It is very important to keep the distance between MIC and cutting area as far as possible to avoid the cutting stive entering into MEMS, otherwise this could contaminate the microphone.



## 13 Output Inspection Standard

Output inspection standard is executed according to <<ISO2859-1:1999>>.